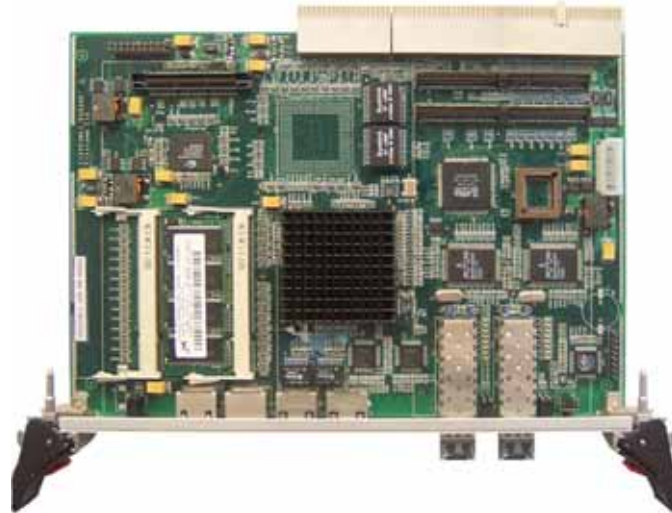


# Flexcomm FIDS23MC1 System

2 Giga PICMG2.16 board for SOHO Router/ Firewall / IDS



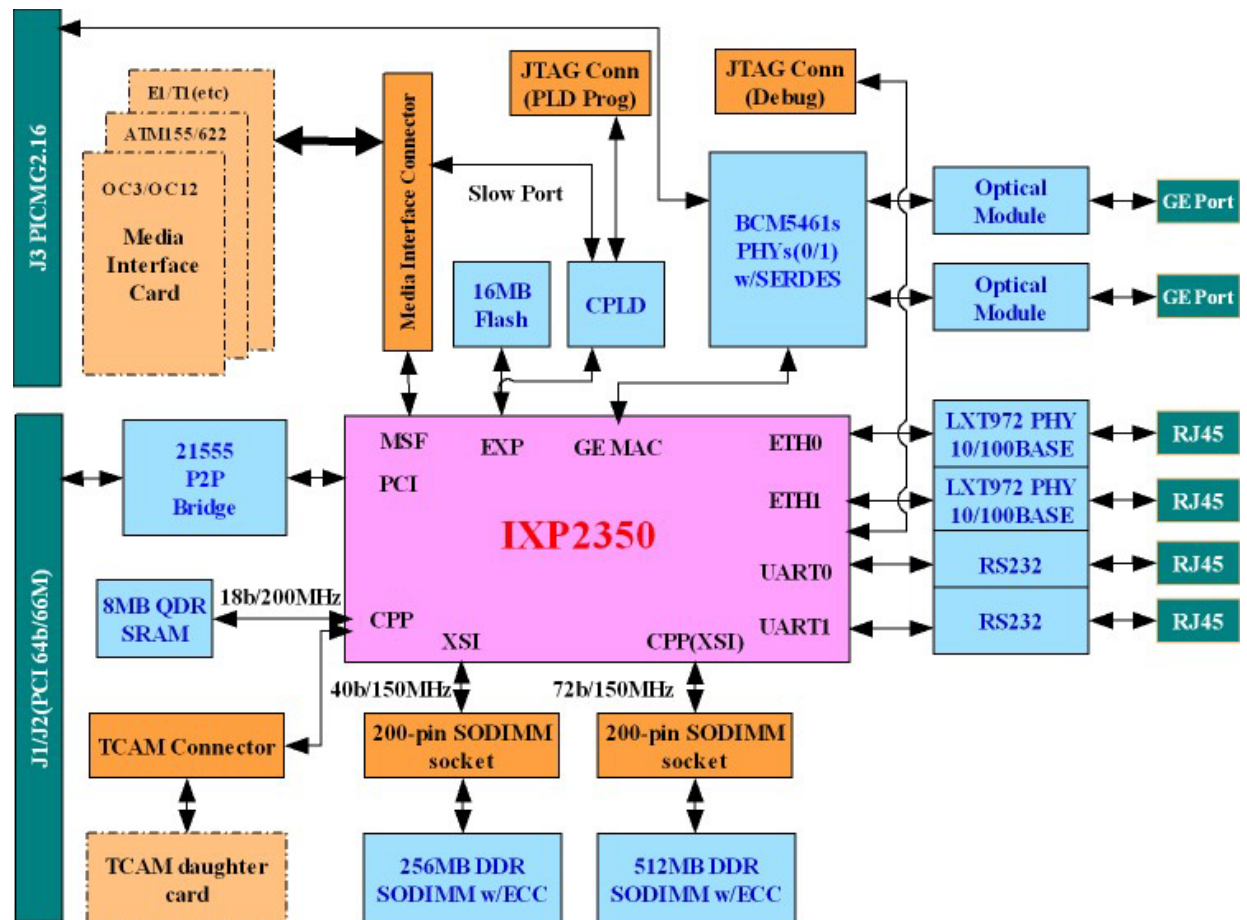
## Product Overview

Based on Intel IXP2350 network processor, which delivers high-performance and flexibility to value-add services because of its powerful parallel and programmable multi micro-engines, FIDS23MC1 is a low-cost yet powerful and fully-featured, production-ready reference platform. In conjunction with Flexcomm's powerful software support and various reference designs, combined with Flexcomm's strong experience in design and develop on Intel IXP serial network processors, FIDS23MC1 reference platform enables customers to get custom products to market faster, at lower cost, and with less development risk.

## Product Highlights

- Low-cost single board solution, can be used stand alone with ATX power supply
- cPCI2.16 form factory
- 2 on-board Gigabit Ethernet ports on front panel, can also be switched to cPCI2.16 backplane
- Expansion capability for media interface cards, auxiliary control plane modules, crypto offload
- TCAM interface to accommodate Flexcomm's off-the-shelf TCAM daughter card
- Linux BSP, Redboot and diagnostic provided and supported by Flexcomm
- Application in Flash extended to the IXP2350 by Flexcomm to provide reference application such as 2GE throughput, IPv4/v6 router, security application and others
- Intel SDK support includes core components, resource manager, example ME code – supported by Flexcomm
- Optimized BOM and schematic

## Function Block Diagram



## Hardware Feature Definition

- 900/900M or 900/600M Intel@ IXP2350 network processor
- 16MB StrataFlash, soldered to main board
- 8MB QDR SRAM, soldered to main board
- 512M CPP DDR DRAM (expandable to 2G) via SODIMM
- 256M XSI DDR DRAM (expandable to 1G) via SODIMM
- Support 4.5M/9Mb TCAM
- 2 Gigabit Ethernet based on Broadcom BCM5461s, fiber supported to front panel on FIDS23MC1 board, can also switched to cPCI2.16 backplane
- 2 10/100 Fast Ethernet management ports and 2 UART console ports
- MSF expansion to support OC3/12, and T1/E1 applications etc
- Stand alone with ATX power supply
- Maximum 25W power consumption
- Redboot and diagnostic binary code in flash

### **FIDS23MC1 HDK features**

- Optimized BOM
- Schematic (PDF file)

### **FIDS23MC1 SDK features**

- Redboot source code
- Diagnostic source code
- 2GE throughput reference application source code
- FIDS23MC1 LSP patch for MVL 3.X
- FIDS23MC1 ramdisk source code
- FIDS23MC1 user manual
- FIDS23MC1 2GE throughput reference design guide

### **Flexcomm Access**

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WEB page      [www.flexcomm.com.cn](http://www.flexcomm.com.cn)

Contact Info:      sales@flexcomm.com.cn

Phone              +86-21-54109960

Address:            12F, Xu Hui Yuan Building, No. 1089 Zhongshan No.2 Road(S),  
Shanghai, China